IMPACT
International Microsystems, Packaging, Assembly and Circuits Technology conference

IMPACT-EMAP 2014

Oct 22-24, 2014 Taipei

Call for Papers

Accepted Papers Will Be Collected in IEEE Xplore !

CEA identifies the five tech trends for 2014: the Internet of Things (IoT), driverless cars, digital health care, robotics and content curation. The research report shows their potential to enrich our lives, and in some cases, massively change them. To reflect the cutting-edges technology development, the theme of IMPACT-EMAP 2014 highlights "Challenge for Change-Shaping the Future" and will arrange keynote speeches, invited talks, industrial sessions and outstanding paper presentations. The IMPACT Conference is the largest gathering of packaging and PCB professionals in Taiwan, attracting over 3,600 attendees in accumulated total over the past few years.

This year, the 9th IMPACT (International Microsystems, Packaging, Assembly, Circuits Technology) Conference will be held in conjunction with the 16th EMAP (International Conference on Electronics Materials and Packaging) which just rotates to Taipei. IMPACT Conference keeps collaborating with International organizations such as ICEP from Japan and iNEMI from U.S.A. The IMPACT Conference is an amazing convergence of microsystems knowledge and community via bridging the industries and academia. IMPACT is committed to helping you fulfill your increasingly demanding role in the R&D department, and providing more contents relevant to your needs and goals than ever before!

Conference: IMPACT-EMAP 2014
Exhibition: TPCA Show 2014
Theme: Challenge for Change-Shaping the Future

Date: Oct 22 (Wed)-24(Fri), 2014
Venue: Taipei Nangang Exhibition Center
On-line Submission: www.impact.org.tw

IMPORTANT DATE

Item	Date	Remark
Abstract Submission Deadline	June 15, 2014	400-500 words Submit on-line through conference website
Abstract Acceptance Notification	July 14, 2014	Notice sent via email
Online Registration Opens	July 28, 2014	
Advance Program Online	August 11, 2014	Advanced program announcement
Full Paper Submission (Camera-ready Version)	August 15, 2014	4 pages including figures and tables Submit on-line through conference website and copyright forms due

* Authors of accepted papers including oral presentation and posters should register before the deadline; please be noted that un-registered (paid) papers will be removed from the symposium program.
* The secretariat keeps the right to modify the agenda.

SCOPE OF PAPER SOLICITED

IMPACT

Packaging	PCB
P1. Advanced Packaging Technologies	B1. Green Materials and Process
P2. Green Packaging	B2. Test, Quality, Inspection and Reliability Technology
P3. 3D Integration	B3. HDI and Embedded Technology
P4. LED & Optoelectronics Packaging	B4. Electro Deposition and Electrochemical Processing Technology
P5. Interconnections & Nanotechnology	B5. Advanced and Emerging Technology
P6. Modeling, Simulation & Design	B6. Mechatronics and Automation
P7. hermal Management	B7. Marketing & Management
P8. Advanced Sensor & Microsystems Technology (MST)	
P9. Advanced Materials, Automatic Process & Assembly	
P10. Emerging Systems Packaging Technologies	

EMAP

Materials and Packaging	
M1. Materials and Processing	M8. System-in-Package (SiP) and 3D Stacked Die Packaging
M2. Passive and Active Components	M9. Electrical Modeling, Characterization, and Signal
M3. Optoelectronics / Photonics	M10. Thermal-Mechanical Modeling and Characterization
M4. Sensor, Actuator, and Transducer Technologies	M11. Quality and Reliability
M5. Advanced Packaging	M12. Packaging Technologies for High Brightness LEDs
M6. Thru Silicon Via (TSV) Technology	M13. Flexible Electronics
M7. Interconnection Technologies	M14. Others

* Papers relevant with the above scopes are encouraged to submit but NOT limited to. * Conference authority keeps the right to final session arrangement.

PAPER AWARD

Best Student Paper Award and Outstanding Paper Award will be elected by IMPACT Technical Program Committee from student and industrial papers respectively. The paper awardees will be announced and honored at the conference.

SPONSOR

IMPACT 2014 sponsors can improve the corporate image, enhance professional development, create networking opportunities and enjoy exclusive benefits. There are multiple sponsorship packages for you to choose!

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